

**KBP2005G THRU KBP210G
SINGLE PHASE 2.0AMP GLASS PASSIVATED BRIDGE RECTIFIER**

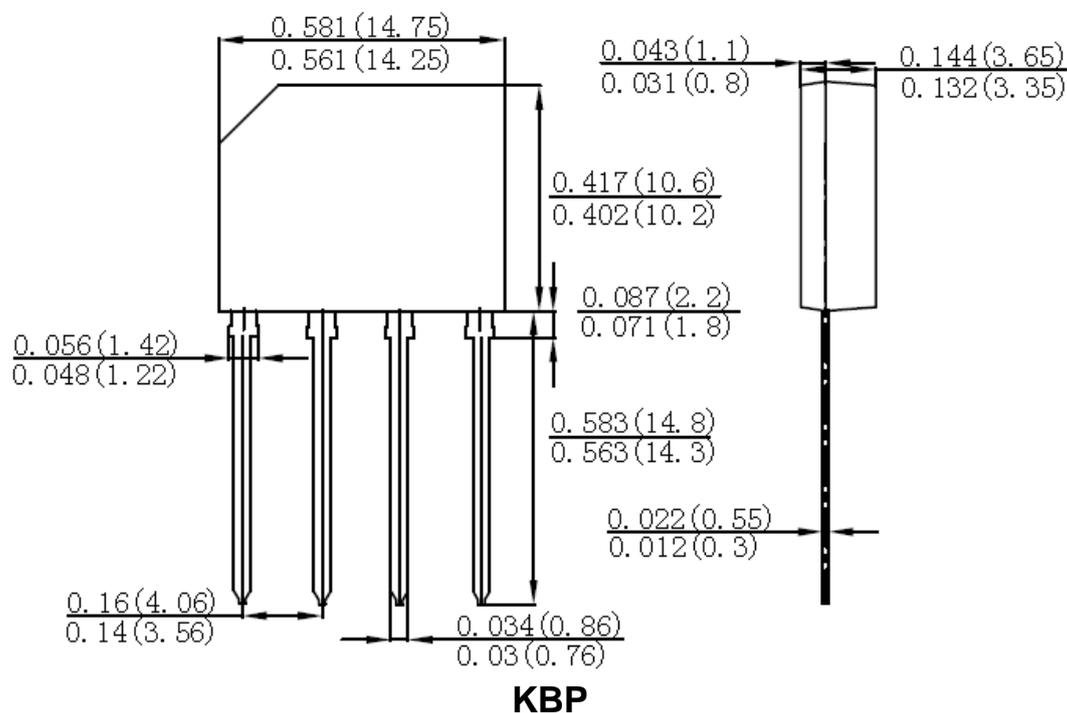
Features:

- Glass passivated die construction
- Low forward voltage drop
- High current capability
- High surge current capability
- Plastic material-UL flammability 94V-0

Mechanical Data:

- Case: KBP, molded plastic
- Terminals: plated leads solderable per MIL-STD-202, Method 208
- Polarity: as marked on case
- Mounting position: Any
- Lead Free: For RoHS / Lead Free Version

Mechanical Dimensions: In mm/Inches



MARKING, MOLDING RESIN

Marking for Type Number, 1st row SSG YYWWL, 2nd row Type Number
Where YY is the manufacture year
WW is the manufacture week code
L is the wafer's Lot Number



Maximum Ratings and Electrical Characteristics Rating at 25°C ambient temperature unless otherwise specified. Single Phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%

Maximum Ratings:

Type number	Symbol	KBP 2005G	KBP 201G	KBP 202G	KBP 204G	KBP 206G	KBP 208G	KBP 210G	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
RMS Reverse Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Average Rectified Output Current @ $T_A=50^\circ\text{C}$	I_o	2.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	60							A

Electrical Characteristics:

Type Number	Symbol	KBP 2005G	KBP 201G	KBP 202G	KBP 204G	KBP 206G	KBP 208G	KBP 210G	Unit
Forward Voltage per element @ $I_F=2.0\text{A}$	V_F	1.1							V
Peak Reverse Current @ $T_A=25^\circ\text{C}$ At Rated DC Blocking Voltage @ $T_A=125^\circ\text{C}$	I_R	5.0 500							μA

Thermal-Mechanical Specifications:

Type Number	Symbol	KBP 2005G	KBP 201G	KBP 202G	KBP 204G	KBP 206G	KBP 208G	KBP 210G	Unit
Typical Thermal Resistance Junction to Ambient (Note 1)	$R_{\theta JA}$	25							$^\circ\text{C/W}$
Typical Thermal Resistance Junction to Lead (Note 1)	$R_{\theta JL}$	8							
Junction Temperature	T_J	-55 to +150							$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55 to +150							$^\circ\text{C}$
Case Style		KBP							

Note: 1. Mounted on glass epoxy PC board with 1.3mm² solder pad.

**Technical Data
Data Sheet N1746, Rev. -**

Fig. 1 Forward Current Derating Curve

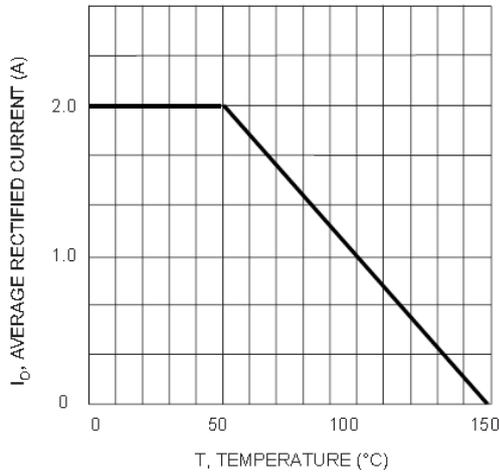


Fig. 2 Typical Fwd Characteristics

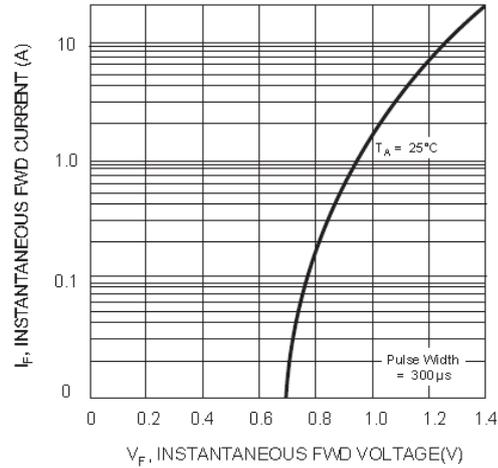


Fig. 3 Max Non-Repetitive Peak Fwd Surge Current

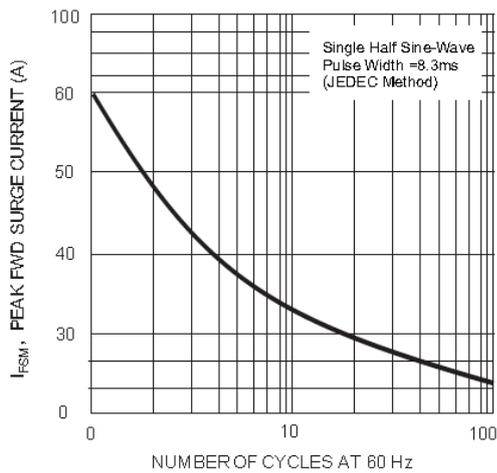


Fig. 4 Typical Junction Capacitance

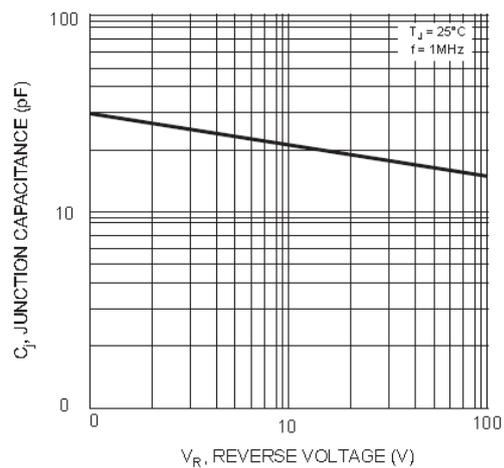
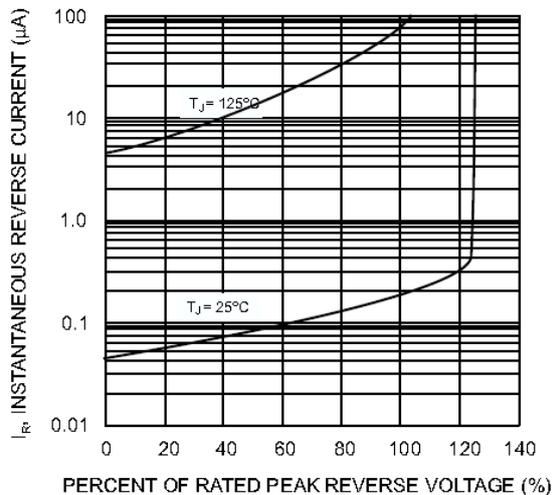


Fig. 5 Typical Reverse Characteristics (per element)





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Green Products

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